

PROCESS CAPABILITY

GIVEN: A VARIABLE TO BE TRACKED, For example, the diameter of a machined part:

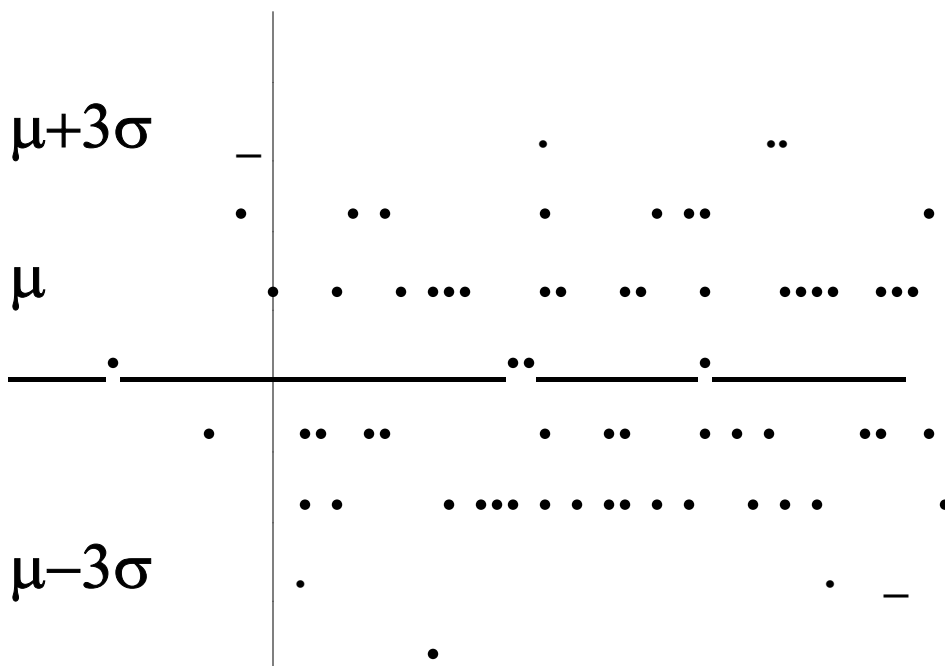
Let T =Target Diameter

USL= Upper Specification Limit

LSL= Lower Specification Limit

Collect some data for the diameters, X_1, \dots, X_n

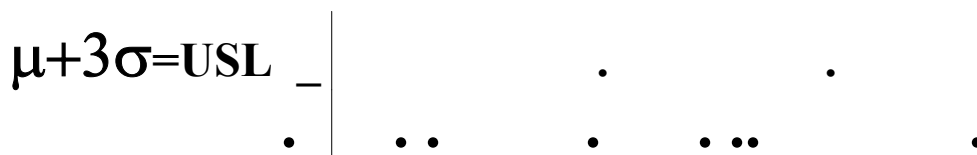
Suppose $\mu = \sum X_i / n$, $\sigma = \sqrt{\sum (X_i - \mu)^2 / (n-1)}$.

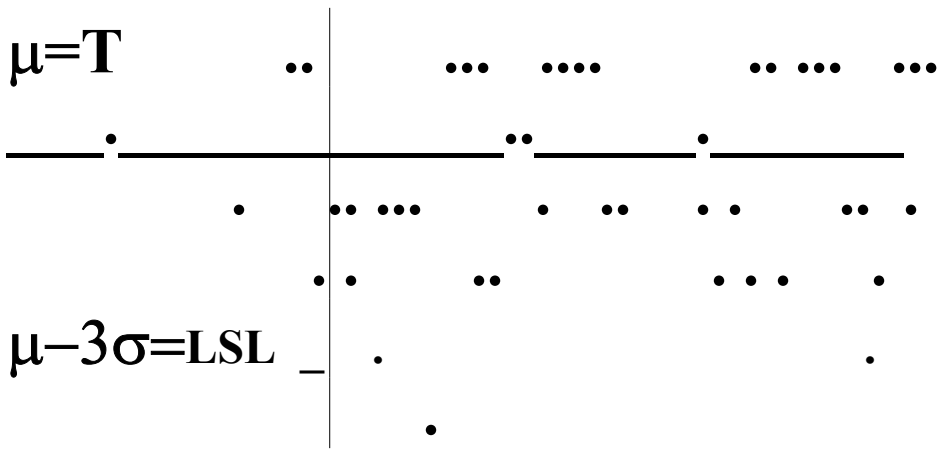


How well is the process performing?

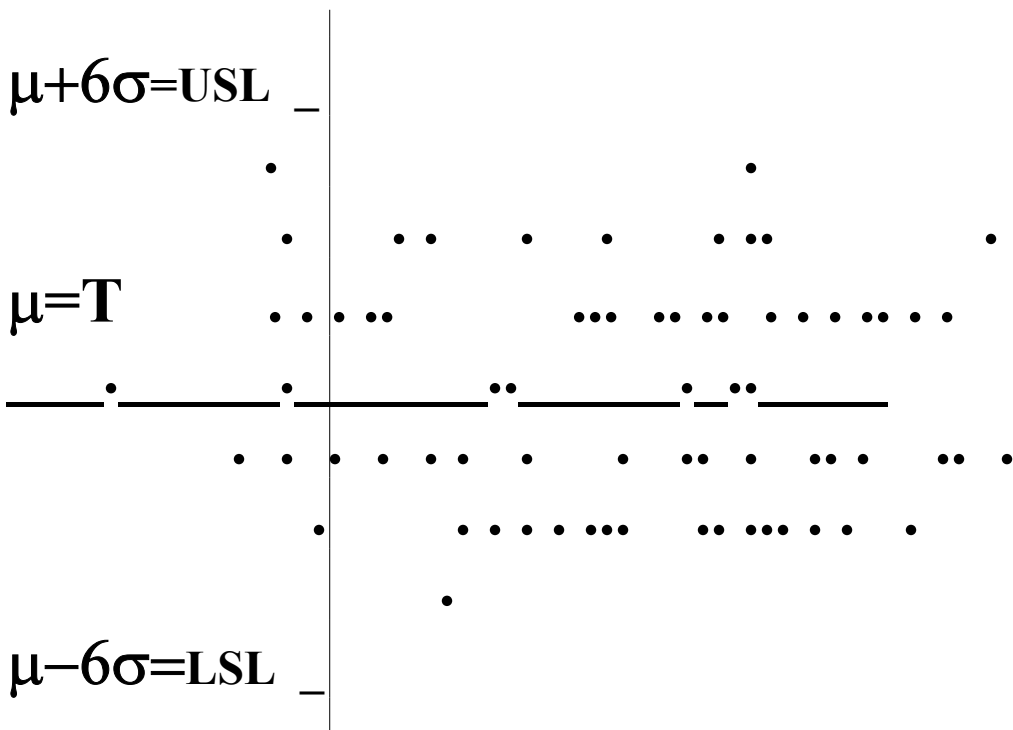
One Measure: $C_p = (USL - LSL) / 6\sigma$

If $\mu = T$, $\mu + 3\sigma = USL$, and $\mu - 3\sigma = LSL$, then, $C_p = 1$.





If $\mu = T$, $\mu + 6\sigma = USL$, and $\mu - 6\sigma = LSL$, then, $C_p = 2$.



Which is better, $C_p = 1$ or $C_p = 2$?

Define $C_{pk} = \min\{(USL - \mu)/3\sigma, (\mu - LSL)/3\sigma\}$

Suppose $T + 3\sigma = USL$ and $T - 3\sigma = LSL$.

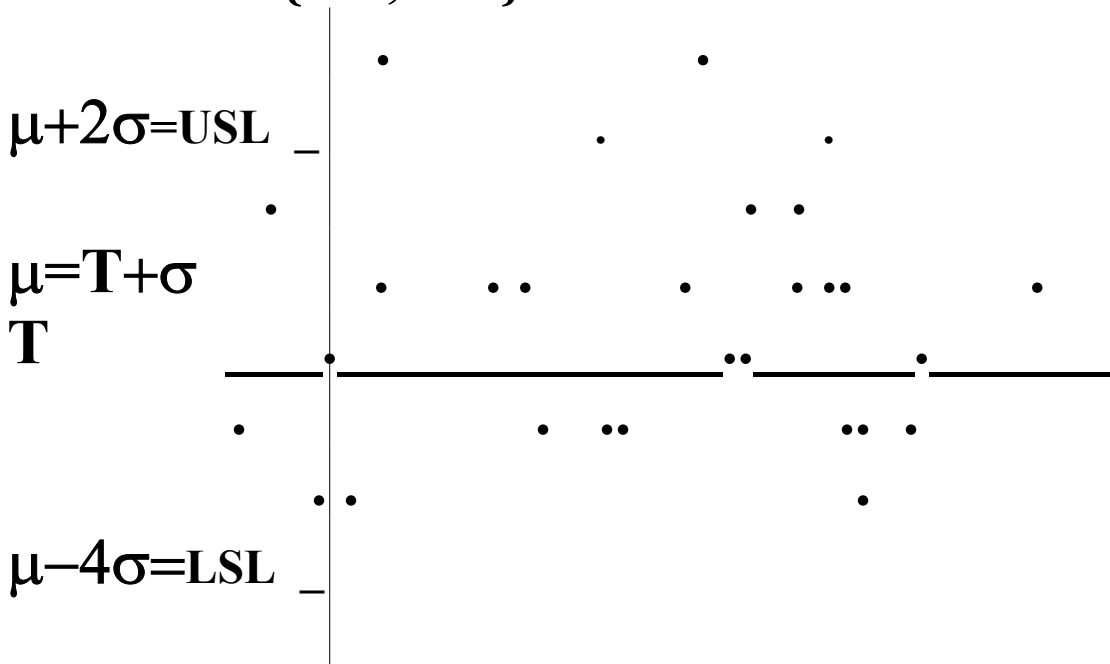
If $\mu = T$, then $C_p = C_{pk}$

If $\mu > T$, e.g., if $\mu = T + \sigma$, then

$$C_p = (T + 3\sigma - T - 3\sigma) / 6\sigma = 1$$

$$C_{pk} = \min\{(T + 3\sigma - T - \sigma) / 3\sigma, (T + \sigma - T + 3\sigma) / 3\sigma\}$$

$$= \min\{2/3, 4/3\} = 2/3.$$



Which measure do you prefer?

At Motorola, *6σ program* aims for $C_{pk} = 2$ for all processes. What defect frequency does that imply? (Hint: $Z \sim N(0,1) = 6 \Rightarrow$ area under curve = .4999983.)